

ESD5451XZ

1-Line, Bi-directional, Transient Voltage Suppressors

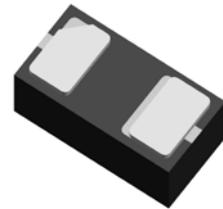
<http://www.sh-willsemi.com>

Descriptions

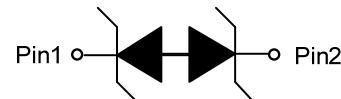
The ESD5451XZ is a bi-directional TVS (Transient Voltage Suppressor). It is specifically designed to protect sensitive electronic components which are connected to low speed data lines and control lines from over-stress caused by ESD (Electrostatic Discharge), EFT (Electrical Fast Transients) and Lightning.

The ESD5451XZ may be used to provide ESD protection up to $\pm 30\text{kV}$ (contact and air discharge) according to IEC61000-4-2, and withstand peak pulse current up to 8A (8/20 μs) according to IEC61000-4-5.

The ESD5451XZ is available in FBP0603-2L package. Standard products are Pb-free and Halogen-free.



FBP0603-2L (Bottom View)



Circuit diagram



A = Device code

* = Month code

Marking (Top View)

Features

- Reverse stand-off voltage: $\pm 5\text{V}$ Max
- Transient protection for each line according to IEC61000-4-2 (ESD): $\pm 30\text{kV}$ (contact and air discharge)
- IEC61000-4-4 (EFT): 40A (5/50ns)
- IEC61000-4-5 (surge): 8A (8/20 μs)
- Capacitance: $C_J = 17.5\text{pF}$ typ.
- Low leakage current: $I_R < 1\text{nA}$ typ.
- Low clamping voltage: $V_{CL} = 9\text{V}$ typ. @ $I_{PP} = 16\text{A}$ (TLP)
- Small package

Applications

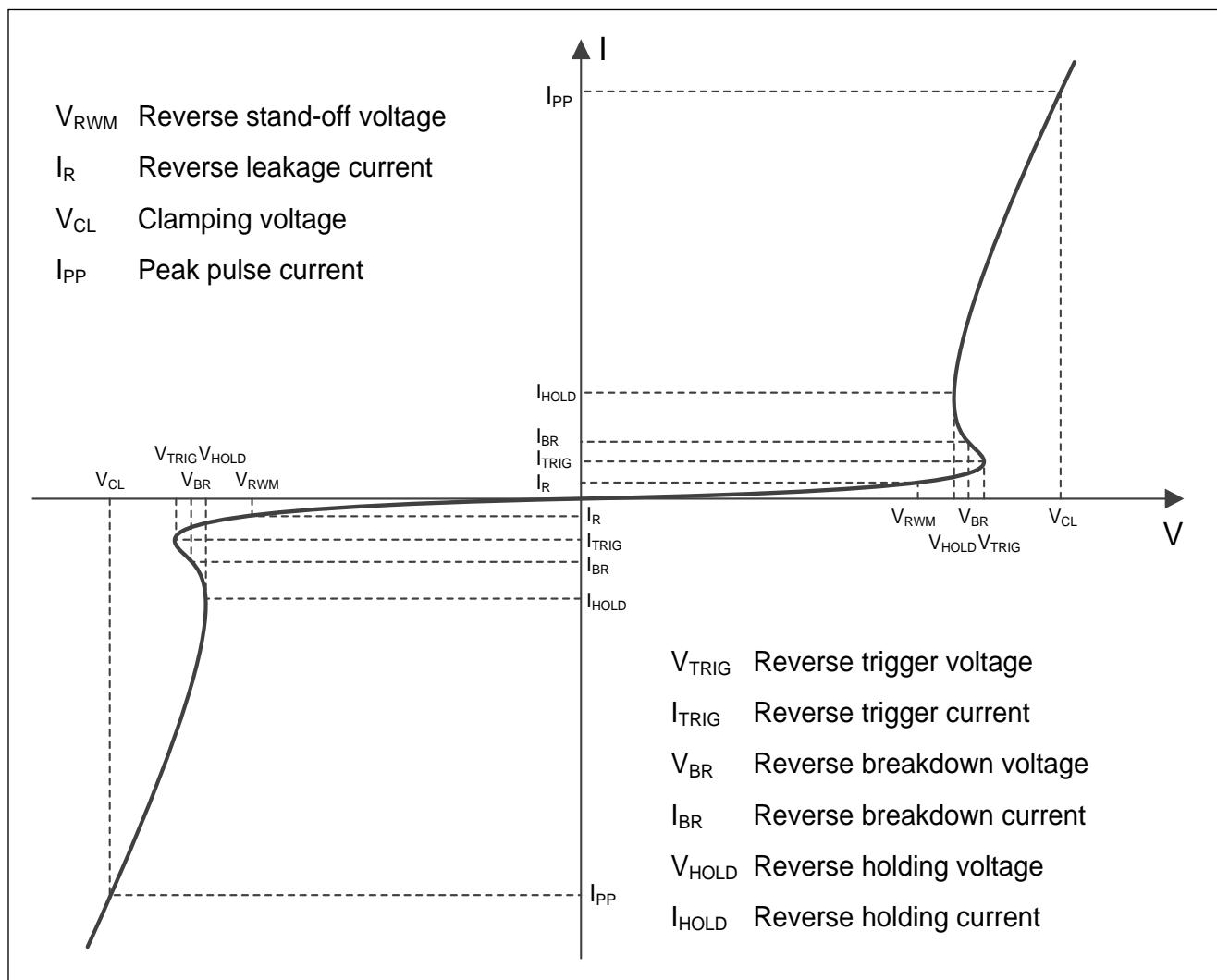
- Cellular handsets
- Tablets
- Laptops
- Other portable devices
- Network communication devices

Order information

Device	Package	Shipping
ESD5451XZ-2/TR	FBP0603-2L	10000/Tape&Reel

Absolute maximum ratings

Parameter	Symbol	Rating	Unit
Peak pulse power ($t_p = 8/20\mu s$)	P_{pk}	80	W
Peak pulse current ($t_p = 8/20\mu s$)	I_{PP}	8	A
ESD according to IEC61000-4-2 air discharge	V_{ESD}	± 30	kV
ESD according to IEC61000-4-2 contact discharge		± 30	
Junction temperature	T_J	125	$^{\circ}C$
Operating temperature	T_{OP}	-40~85	$^{\circ}C$
Lead temperature	T_L	260	$^{\circ}C$
Storage temperature	T_{STG}	-55~150	$^{\circ}C$

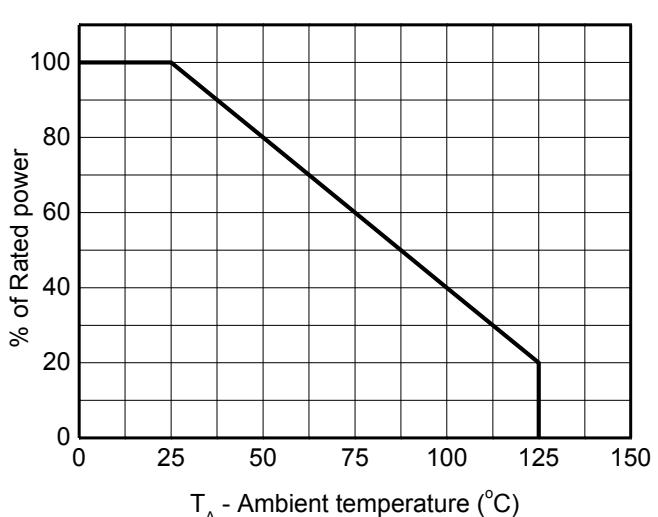
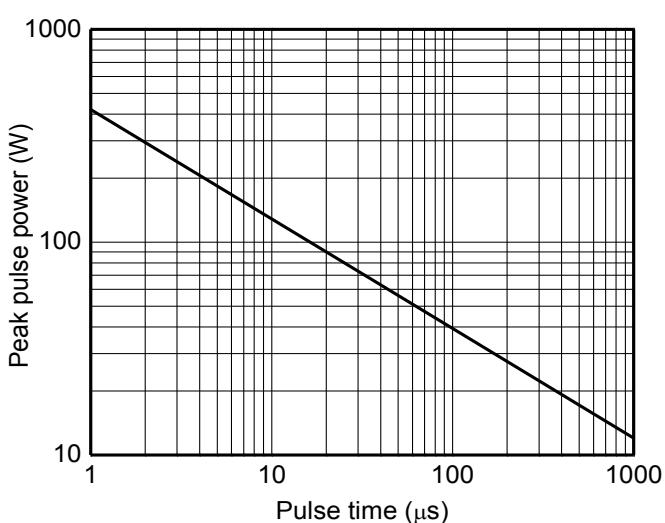
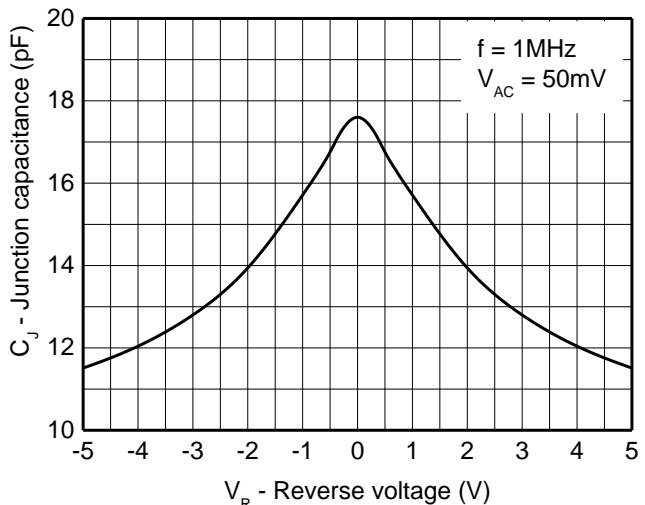
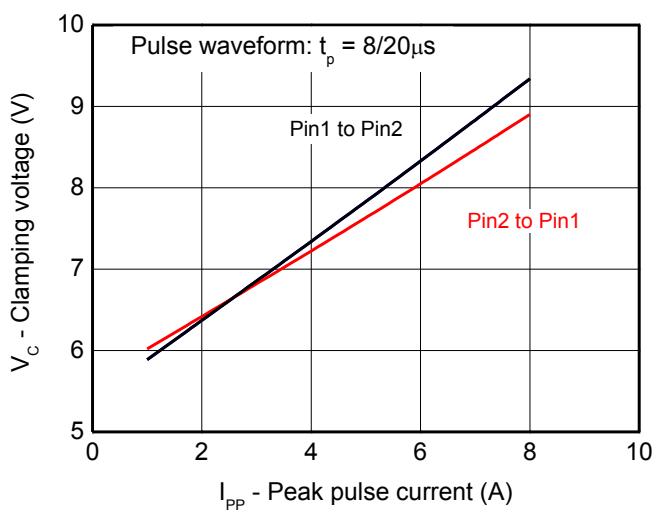
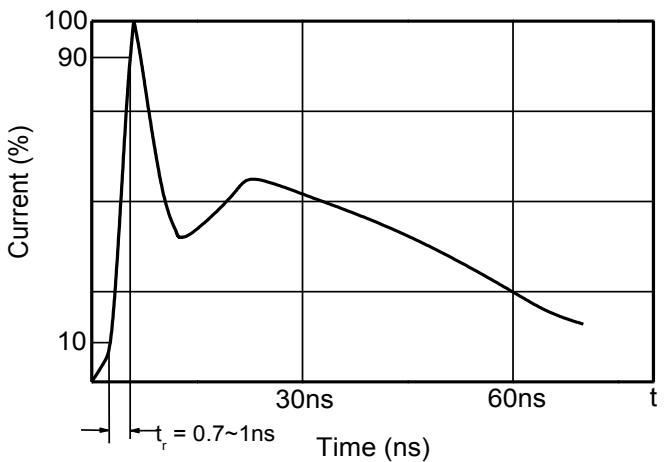
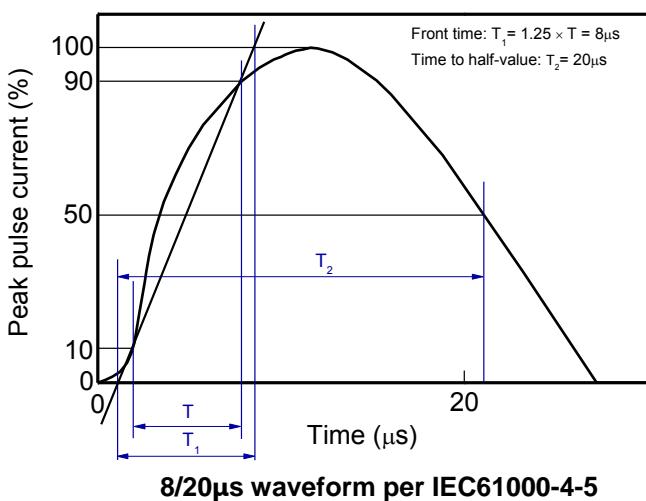
Electrical characteristics ($T_A=25^{\circ}C$, unless otherwise noted)

Definitions of electrical characteristics

Electrical characteristics ($T_A=25^\circ\text{C}$, unless otherwise noted)

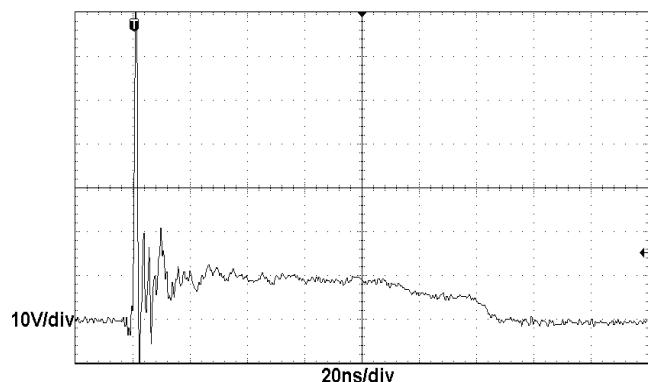
Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Reverse stand-off voltage	V_{RWM}				± 5.0	V
Reverse leakage current	I_R	$V_{RWM} = 5.0\text{V}$		<1	100	nA
Reverse breakdown voltage	V_{BR}	$I_{BR} = 1\text{mA}$	5.1			V
Reverse holding voltage	V_{HOLD}	$I_{HOLD} = 50\text{mA}$	5.1			V
Clamping voltage ¹⁾	V_{CL}	$I_{PP} = 16\text{A}, t_p = 100\text{ns}$		9		V
Clamping voltage ²⁾	V_{CL}	$V_{ESD} = 8\text{kV}$		9		V
Clamping voltage ³⁾	V_{CL}	$I_{PP} = 1\text{A}, t_p = 8/20\mu\text{s}$			6.5	V
		$I_{PP} = 5\text{A}, t_p = 8/20\mu\text{s}$			8.5	V
		$I_{PP} = 8\text{A}, t_p = 8/20\mu\text{s}$			10	V
Dynamic resistance ¹⁾	R_{DYN}			0.20		Ω
Junction capacitance	C_J	$V_R = 0\text{V}, f = 1\text{MHz}$		17.5	22	pF
		$V_R = 5.0\text{V}, f = 1\text{MHz}$		11.5	16	pF

Notes:

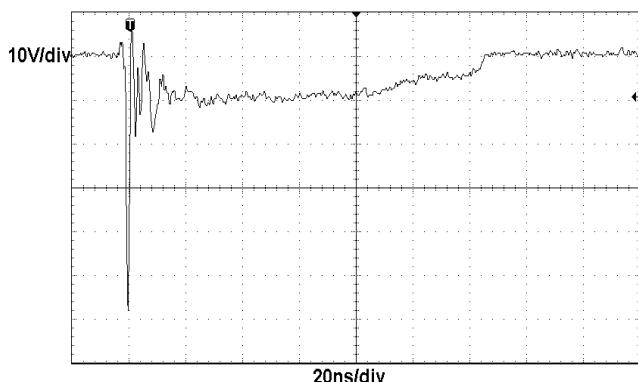
- 1) TLP parameter: $Z_0 = 50\Omega$, $t_p = 100\text{ns}$, $t_r = 2\text{ns}$, averaging window from 60ns to 80ns. R_{DYN} is calculated from 4A to 16A.
- 2) Contact discharge mode, according to IEC61000-4-2.
- 3) Non-repetitive current pulse, according to IEC61000-4-5.

Typical characteristics ($T_A=25^\circ\text{C}$, unless otherwise noted)


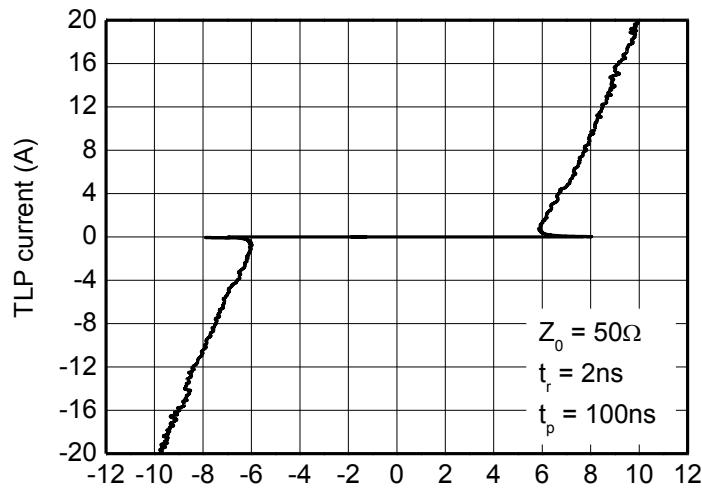
Typical characteristics ($T_A=25^\circ\text{C}$, unless otherwise noted)



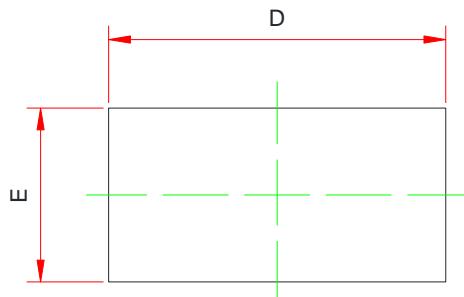
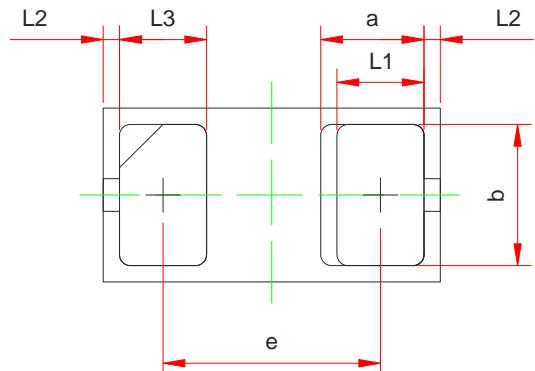
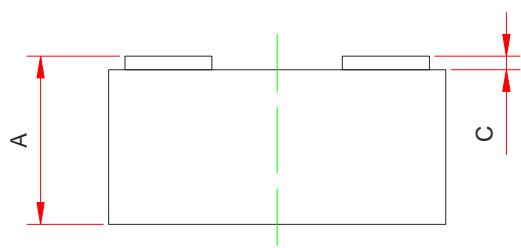
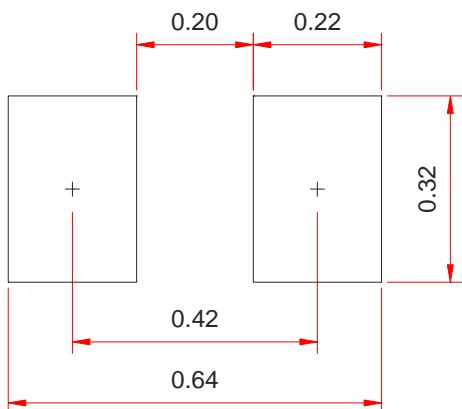
ESD clamping
(+8kV contact discharge per IEC61000-4-2)



ESD clamping
(-8kV contact discharge per IEC61000-4-2)



TLP Measurement

Package outline dimensions
FBP0603-2L

Top View

Bottom View

Side View
Recommend land pattern (Unit: mm)


Symbol	Dimensions in millimeter		
	Min.	Typ.	Max.
A	0.275	-	0.340
D	0.570	-	0.670
a 0.190 REF.			
E	0.270	-	0.370
b	0.225	-	0.295
c	0.010	-	0.090
e	0.365		0.435
L1	0.125	-	0.195
L3	0.125	-	0.195
L2	0.030 REF.		

Notes:

This recommended land pattern is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met.